Development of Top/Bottom Counting Detectors for the CREAM Experiment on the ISS

H. J. HYUN¹, T. ANDERSON², D. ANGELASZEK³, J. B. BAE¹, S. J. BAEK⁴, M. COPLEY³, S. COUTU², M. GUPTA3, J. H. HAN³, H. G. HUH³, Y. S. HWANG¹, I. S. JEONG⁴, D. H. KAH¹, K. H. KANG¹, H. J. KIM¹*, K. C. KIM³, K. KWASHNAK³, J. LEE⁴, M. H. LEE³, J. T. LINK^{5,6}, L. LUTZ³, A. MALINE³, J. W. MITCHELL⁵, S. NUTTER⁷, O. OFOHA³, H. PARK¹, I. H. PARK⁴, J. M. PARK¹, P. PATTERSON³, E. S. SEO³, J. WU³, Y. S. YOON³

1 Kyungpook National University, Daegu 702-701, South Korea / 2 Pennsylvania State University, University Park, PA 16802, USA / 3. University of Maryland, College Park, MD 20740, USA / 4. Sungkyunkwan University, Suwon 440-746, South Korea / 5. NASA GSFC, Greenbelt, MD 20771, USA / 6. CRESST(USRA), Columbia, MD 21044, USA / 7. Northern Kentucky University, Highland Heights, KY41099, USA

Introduction

The ISS-CREAM (Cosmic Ray Energetics) And Mass on the International Space



Design of Top and Bottom Counting Detectors

Goals

Electron/proton separation for electron and gamma-ray physics



Station experiment) planned for a launch to the ISS in 2014 to measure the energy spectral features from 10^{12} eV to > 10^{15} eV and composition that might be related to the supernova acceleration limit [1].

ISS-CREAM Instrument

The ISS-CREAM instrument consists of a Silicon Charge Detector (SCD) to identify incident cosmic rays, a sampling tungsten/scintillator calorimeter for energy measurement of all nuclei [2], a segmented Top/Bottom Counting Detector (TCD and BCD) for e/p separation, and a Boronated Scintillator Detector (BSD) for additional e/p separation and detecting neutron signals

Silicon Photo-Diode

- Silicon photo-diodes (PD) is fabricated on 6-inch, high resistivity, <100>, 650 µm thick, and n-type silicon wafers • The real size of the PD is 2.3×2.3 cm² with



- ⇐ by using the difference between electromagnetic and hadronic showers Provide redundant trigger for ISS-CREAM calorimeter
- Provide MIP (Minimum Ionizing Particle) trigger for calibration

Methods

- Plastic scintillators coupled with 2dimensional photo-diode array
- TCD and BCD each has a total of 400 PDs
- 500 \times 500 mm² and 600 \times 600 mm² for TCD and BCD, respectively
- The silicon photo-diode converts scintillation light to electric current, and electron-hole pairs are also produced by penetrating cosmic rays
- The charge signals are amplified by VLSI charge amp/hold circuits (VA-TA)

Dimensions

TCD : 900 × 535 × 30 mm³

Operational principle of the TCD and BCD



Exploded view of the (a) TCD, and (b) BCD



an active area of $2.0 \times 2.0 \text{ cm}^2$

The PDs are fabricated at ETRI (Electronics) and Telecommunications Research Institute) in Daejeon, Korea



n-side p-side Photograph of the photo-diodes on 6-inch and 650 µm thickness silicon wafer

- **Electrical characteristics**
- The leakage current and bulk capacitance of the PDs are measured with a picoammeter and LCZ meter as a function
- of reverse bias voltages, respectively
- The full depletion voltage is found to be below -200 V and the optimal operating voltage is determined to be -250 V
- The leakage current is below 20 nA/cm² at the operating voltage
- Photo response was measured at KRISS (Korea Research Institute of Standards and Science) in Daejeon, Korea
 - The quantum efficiency is obtained to be 60
 - ~ 75 % for the wavelength range from 400 to 450 nm, which is wavelength range of the

BCD : 950 × 651 × 33 mm³

Schematic diagram of the TCD and BCD

Readout Electronics

- VA-TA (VA32HDR-TA32CG3) as a front-end electronics
 - The VA has 32 channels and each channel consists of a charge sensitive amplifier, a slow shaper, and a sample-and-hole circuit
 - The output of all channels is connected to the multiplexer and the signals are serially clocked out
 - The TA is 32 channel low power fast triggering ASIC chip and each channel includes a fast shaper followed by a discriminator, whose threshold is externally adjustable
 - Wire-or'ed output cause a chip-global trigger
- 16 bit ADC (Analog to Digital Converter) digitizes the analog signals of the VA-TA
- Commands from the ISS-CREAM common









and the SNR is better than 70 with commercial electronics

- Radiation hardness test using a 45 MeV proton beam at the KIRAMS (Korea) Institute of Radiological and Medical Sciences) in Seoul, Korea
- Exposed to 1.18×10^{11} protons/cm² (> 5000 rad)
- The leakage current is increased up to about 50 nA/cm² but the quality of the PD does not change in our criteria for the best sensor (<100 nA/cm²)

electronics pass through the FPGA and Signal flows in the TCD and BCD electronics control the TCD and BCD readout electronics



(right)

Using ²⁴¹Am radioactive source, the peak hold delay time is measured and the SNR is measured to be 10 with ⁹⁰Sr source • A noise of the prototype

is about 6000 e-rms

Summary and Plan

- We have developed the TCD and BCD for CREAM, which is planned to launch to the International Space Station in 2014 and various tests for performance and safety assurance are in progress.
- TCD and BCD will be delivered to UMD in September for the system level of integration and tests.

References

[1] E. S. Seo et al., ID 629 (2013) this conference. [2] H. S. Ahn et al., Nucl. Instrum. Methods A 579 (2007) 1034-1053.